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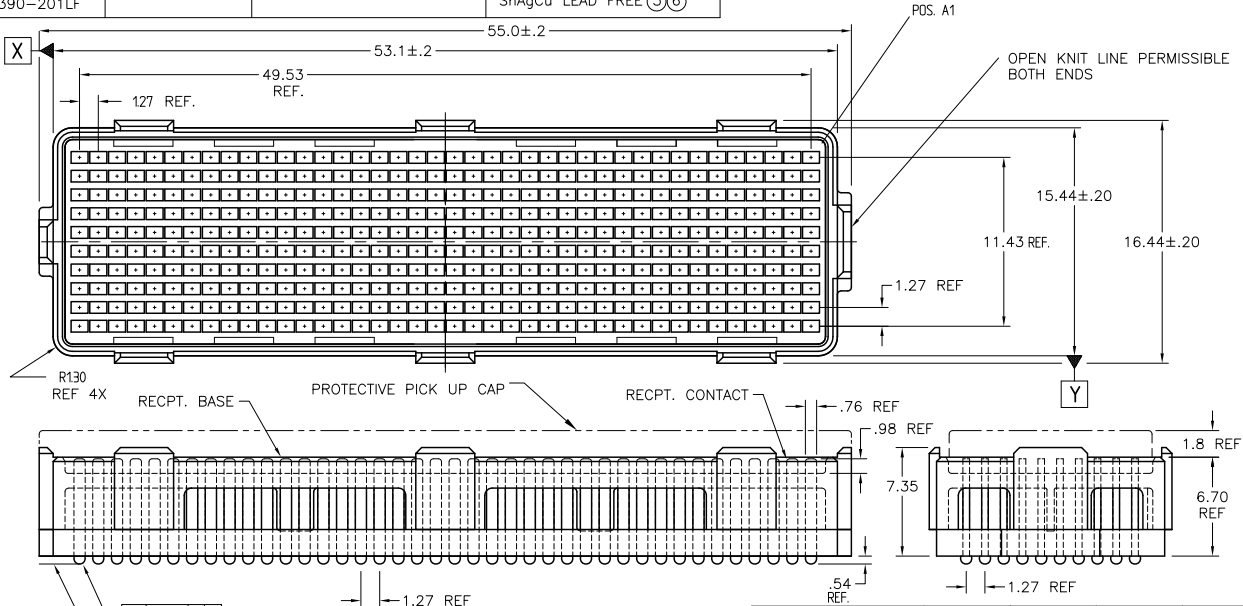
FCIconnect.com

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PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74390-001	YES	15u" (.38um) Au OVER Ni	SnPb
74390-001LF			SnAgCu LEAD FREE (5)(6)
74390-101	YES	30u" (.76um) Au OVER Ni	SnPb
74390-101LF			SnAgCu LEAD FREE (5)(6)
74390-201	YES	SEE NOTE 4.	SnPb
74390-201LF			SnAgCu LEAD FREE (5)(6)



mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ec'n no	ASME Y14.5	ASME Y14.5	MM	MEG-ARRAY
L	V06-0560	LP	2006-06-23	angles	title
M	V09-0493	RE	2009-10-21	XXX+051	8mm RECPT. ASSY
tolerances unless otherwise specified					10 X 40= 400 POS.
scale 3:1					dwg no
FCI logo					sheet 1 of 3
G	V00196	HJ	2000-07-02	dr	74390
H	V20006	BRW	2002-01-03	engr	A4
J	V03-0679	DAI	2003-06-19	chr	type
K	V04-0940	VS	2004-10-18	appd	CUSTOMER Drawing
sheet	revision	M	M	M	
index	sheet	1	2	3	

form A4mmXlc

1

2

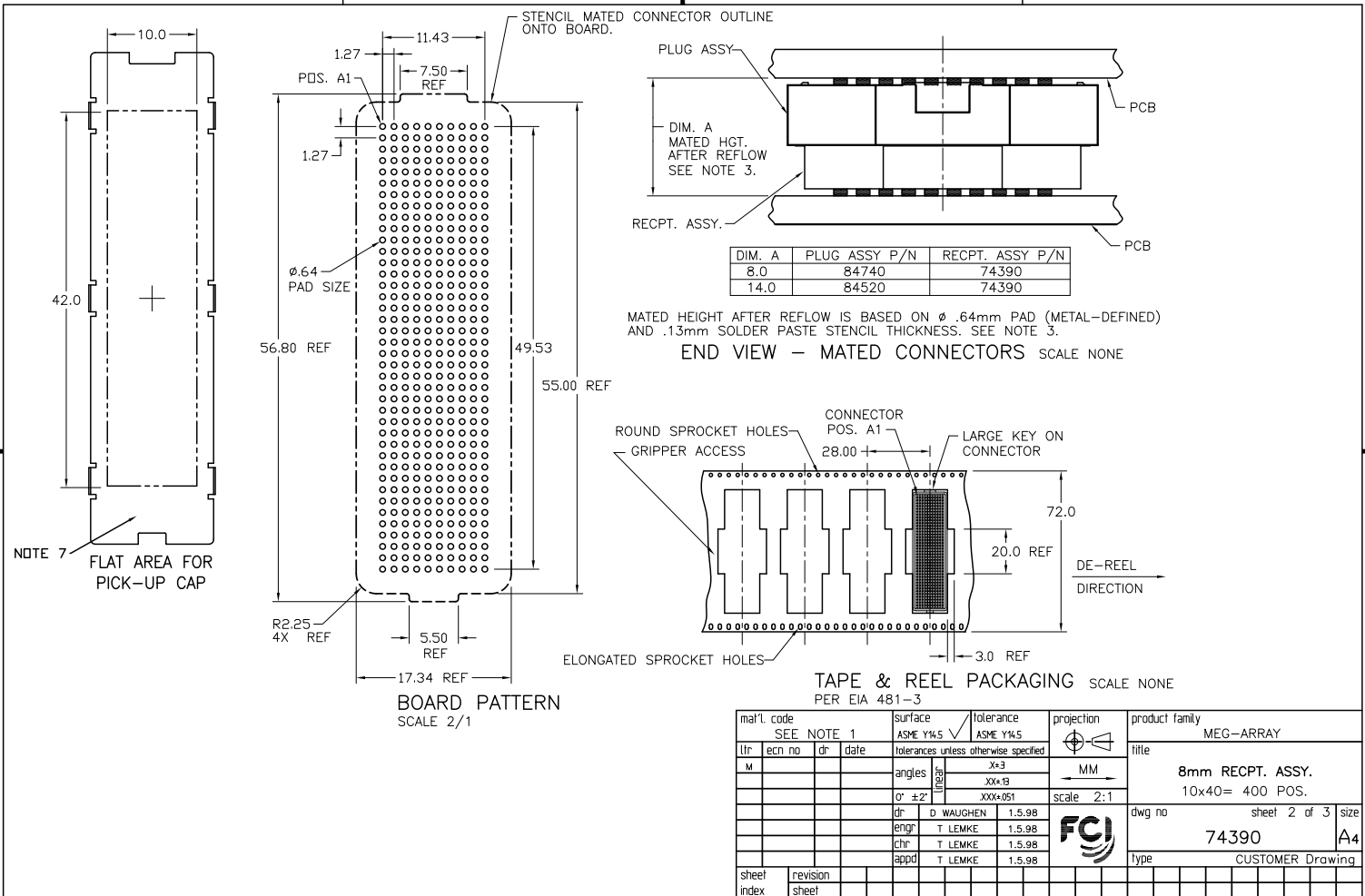
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PDM: Rev:M

STATUS: Released

Printed: Oct 21, 2010



DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
8.0	84740	74390
14.0	84520	74390

MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi .64$ mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ec'n no	dr	date	ASME Y14.5	ASME Y14.5
M				tolerances unless otherwise specified	MM
				angles	X=3
				0° ±2'	XX=19
					XXX=051
		dr	D. WAUGHEN	1.5.98	scale 2:1
		engr	T. LEMKE	1.5.98	
		chr	T. LEMKE	1.5.98	
		appd	T. LEMKE	1.5.98	
sheet index	revision sheet				

product family	MEG-ARRAY
title	8mm RECPT. ASSY. 10x40= 400 POS.
dwg no	74390
sheet	2 of 3
size	A4
type	CUSTOMER Drawing

**NOTES:**

- ①. **MAT'L:**  
HOUSING: LCP  
CONTACT: COPPER ALLOY  
  
**PLATING**  
CONTACT: (SEE TABLE ON SHEET1)  
SOLDER BALL: (SEE TABLE ON SHEET1)  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu
- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑦. COMPANY LOGO TO APPEAR IN THIS AREA.

mat'l. code		SEE NOTE 1		surface	tolerance	projection	product family	
lfr	ecm no	dr	date	ASME Y14.5 ✓	ASME Y14.5		MEG-ARRAY	
M				tolerances unless otherwise specified		MM	title	
				angles	X±3		8mm RECPT. ASSY.	
				0° ±2'	XX±13	scale 2:1	10x40= 400 POS.	
					XXX±051		dwg no	
				dr	D WAUGHEN	FCI	sheet 3 of 3	
				engr	T LEMKE		74390	
				chr	T LEMKE		A4	
				appd	T LEMKE		type	
sheet index	revision sheet						CUSTOMER Drawing	